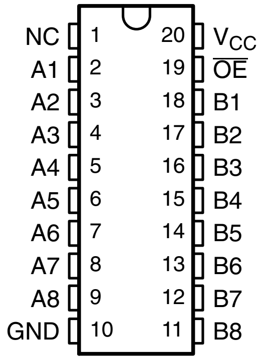
SN74CBT3245A
OCTAL FET BUS SWITCH

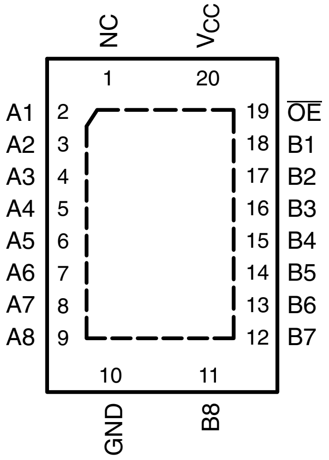
- **Standard ’245-Type Pinout**
- **5-Ω Switch Connection Between Two Ports**
- **TTL-Compatible Input Levels**

DB, DBQ, DGV, DW, OR PW PACKAGE
(TOP VIEW)



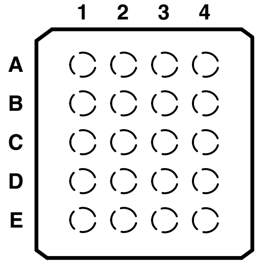
NC – No internal connection

RGY PACKAGE
(TOP VIEW)



NC – No internal connection

GQN OR ZQN PACKAGE
(TOP VIEW)



terminal assignments

	1	2	3	4
A	A1	NC	V_{CC}	$\overline{OE}$
B	A3	B2	A2	B1
C	A5	A4	B4	B3
D	A7	B6	A6	B5
E	GND	A8	B8	B7

NC – No internal connection

description/ordering information

The SN74CBT3245A provides eight bits of high-speed TTL-compatible bus switching. The SOIC, SSOP, TSSOP, and TVSOP packages provide a standard ’245 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as one 8-bit switch. When the output-enable ($\overline{OE}$) input is low, the switch is on, and port A is connected to port B. When $\overline{OE}$ is high, the switch is open, and the high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

description/ordering information (continued)

ORDERING INFORMATION

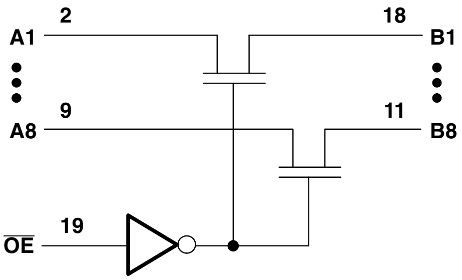
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	QFN – RGY	Tape and reel	SN74CBT3245ARGYR	CU245A
	SOIC – DW	Tube	SN74CBT3245ADW	CBT3245A
		Tape and reel	SN74CBT3245ADWR	
	SSOP – DB	Tape and reel	SN74CBT3245ADBR	CU245A
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3245ADBQR	CBT3245A
	TSSOP – PW	Tube	SN74CBT3245APW	CU245A
		Tape and reel	SN74CBT3245APWR	
	TVSOP – DGV	Tape and reel	SN74CBT3245ADGVR	CU245A
	VFBGA – GQN	Tape and reel	SN74CBT3245AGQNR	CU245A
	VFBGA – ZQN (Pb-free)		SN74CBT3245AZQNR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, PW, and RGY packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}		–0.5 V to 7 V
Input voltage range, V_I (see Note 1)		–0.5 V to 7 V
Continuous channel current		128 mA
Input clamp current, I_{IK} ($V_{I/O} < 0$)		–50 mA
Package thermal impedance, θ_{JA}	(see Note 2): DB package	70°C/W
	(see Note 2): DBQ package	68°C/W
	(see Note 2): DGV package	92°C/W
	(see Note 2): DW package	58°C/W
	(see Note 2): GQN/ZQN package	78°C/W
	(see Note 2): PW package	83°C/W
	(see Note 3): RGY package	37°C/W
Storage temperature range, T_{stg}		–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.
3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	4	5.5	V
V_{IH}	High-level control input voltage	2		V
V_{IL}	Low-level control input voltage		0.8	V
T_A	Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
V_{IK}		$V_{CC} = 4.5$ V,	$I_I = –18$ mA				–1.2	V
I_I		$V_{CC} = 5.5$ V,	$V_I = 5.5$ V or GND				±5	µA
I_{CC}		$V_{CC} = 5.5$ V,	$I_O = 0$,	$V_I = V_{CC}$ or GND			50	µA
ΔI_{CC}§	Control inputs	$V_{CC} = 5.5$ V,	One input at 3.4 V,	Other inputs at V_{CC} or GND			3.5	mA
C_i	Control inputs	$V_I = 3$ V or 0				4		pF
$C_{io(OFF)}$		$V_O = 3$ V or 0,	$\overline{OE} = V_{CC}$			4		pF
r_{on}¶		$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA		5	7	Ω
				$I_I = 30$ mA		5	7	
			$V_I = 2.4$ V,	$I_I = 15$ mA		10	15	

‡ All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25°C$.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

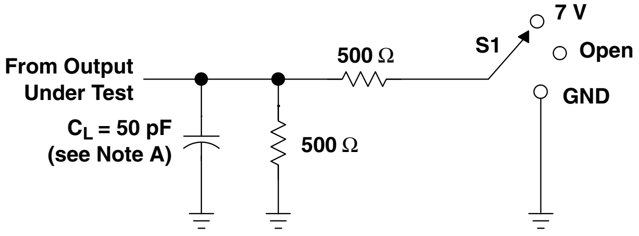
¶ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 4 V		V_{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t_{pd}†	A or B	B or A		0.35		0.25	ns
t_{en}	$\overline{OE}$	A or B		6.4	1.9	5.9	ns
t_{dis}	$\overline{OE}$	A or B		5.7	2.1	6	ns

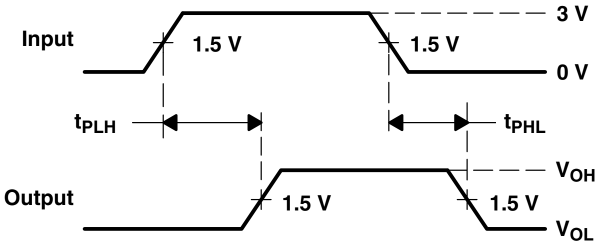
† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION

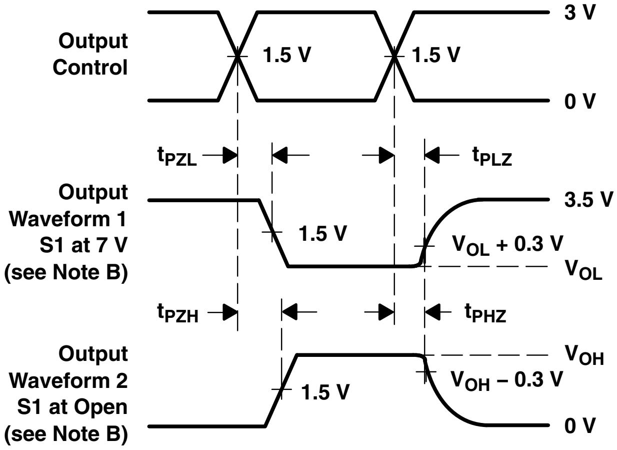


LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

NOTES:
- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74CBT3245ADBR	NRND	Production	SSOP (DB) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU245A
SN74CBT3245ADBR.A	NRND	Production	SSOP (DB) | 20	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU245A
SN74CBT3245ADGVR	Obsolete	Production	TVSOP (DGV) | 20	-	-	Call TI	Call TI	-40 to 85	CU245A
SN74CBT3245ADW	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-40 to 85	CBT3245A
SN74CBT3245ADWR	Obsolete	Production	SOIC (DW) | 20	-	-	Call TI	Call TI	-40 to 85	CBT3245A
SN74CBT3245APW	Obsolete	Production	TSSOP (PW) | 20	-	-	Call TI	Call TI	-40 to 85	CU245A
SN74CBT3245APWR	Obsolete	Production	TSSOP (PW) | 20	-	-	Call TI	Call TI	-40 to 85	CU245A
SN74CBT3245ARGYR	Obsolete	Production	VQFN (RGY) | 20	-	-	Call TI	Call TI	-40 to 85	CU245A
SN74CBT3245ARGYR.B	Obsolete	Production	VQFN (RGY) | 20	-	-	Call TI	Call TI	-40 to 85	CU245A

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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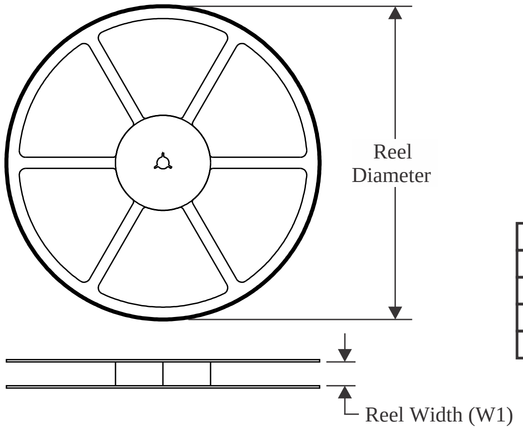
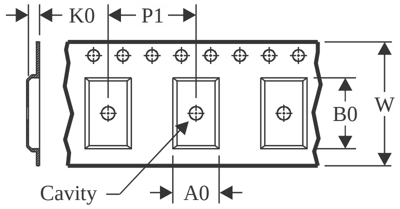
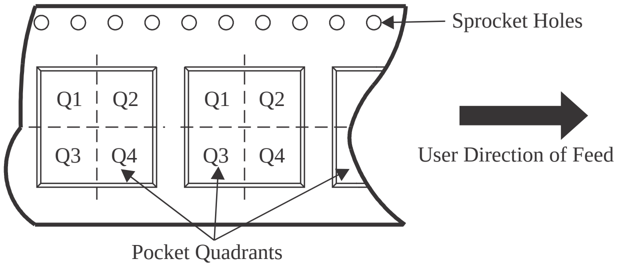
TAPE AND REEL INFORMATION


REEL DIMENSIONS


TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

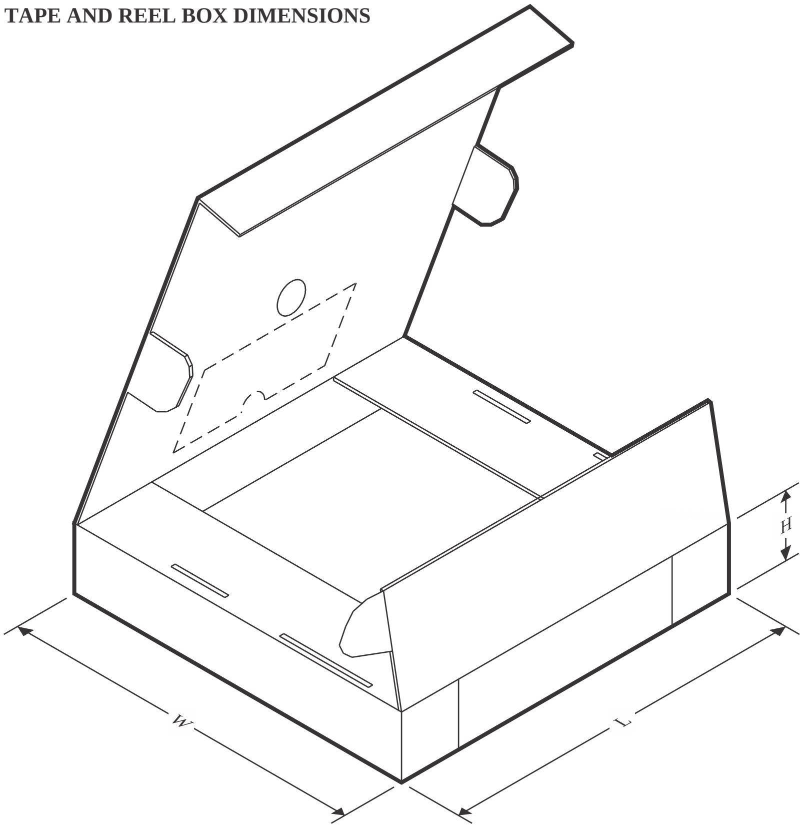
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT3245ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



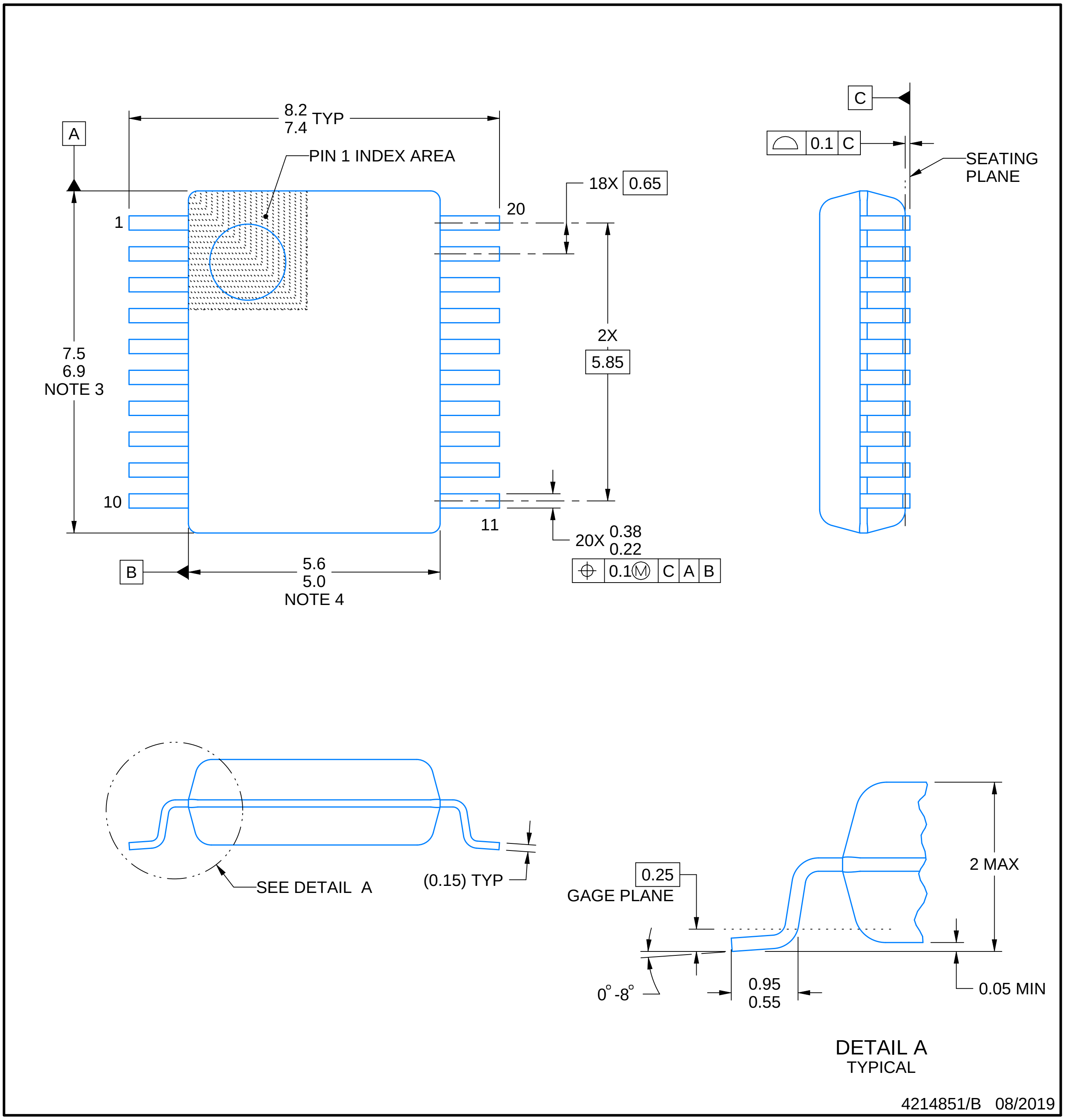
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT3245ADBR	SSOP	DB	20	2000	353.0	353.0	32.0

PACKAGE OUTLINE

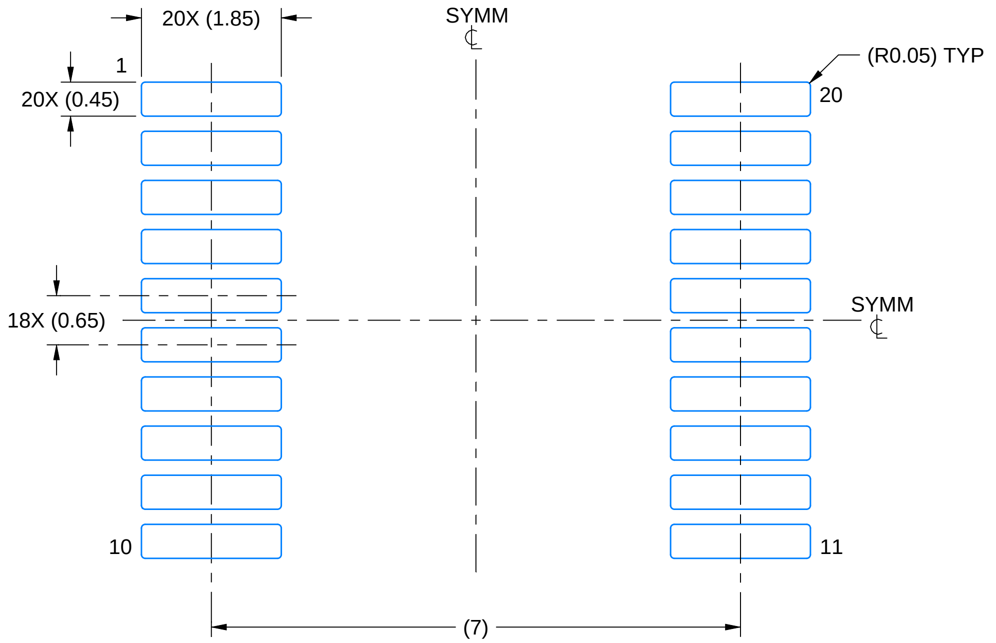
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

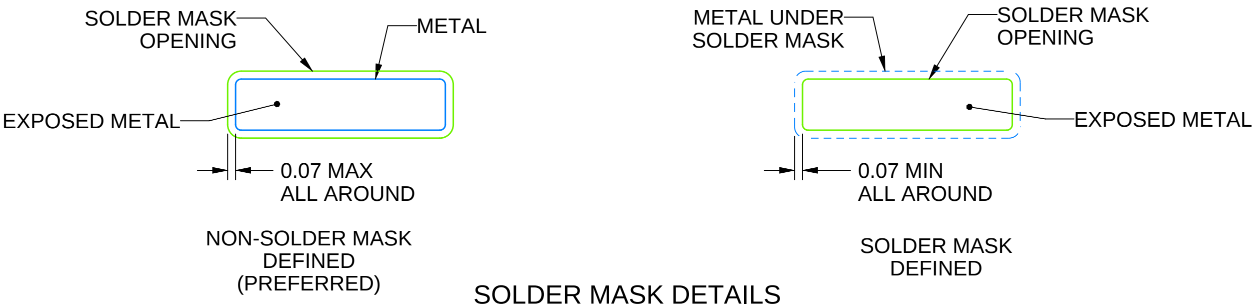


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

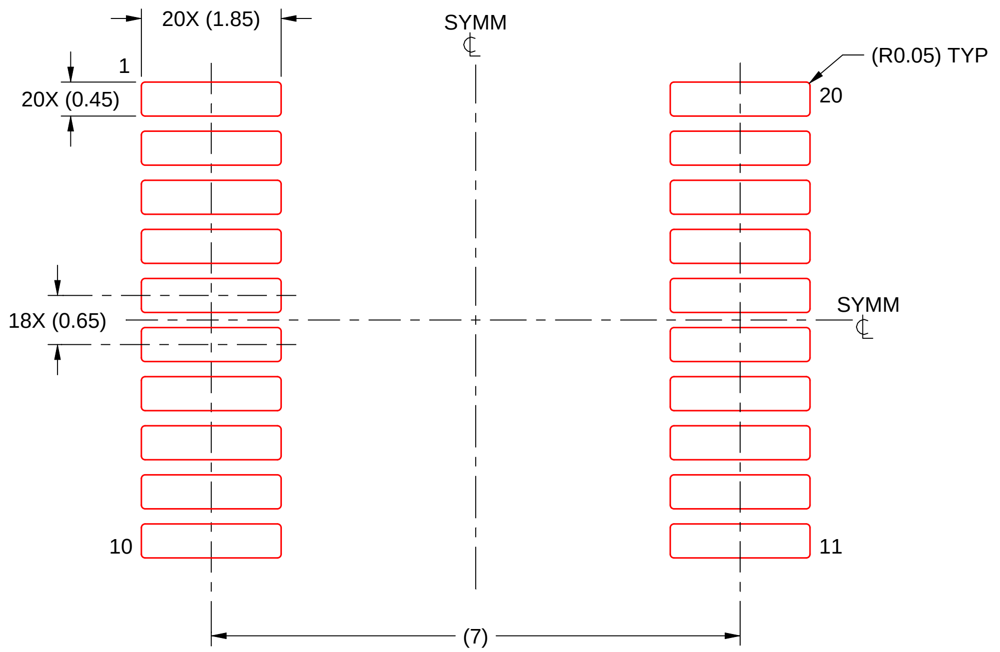


SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



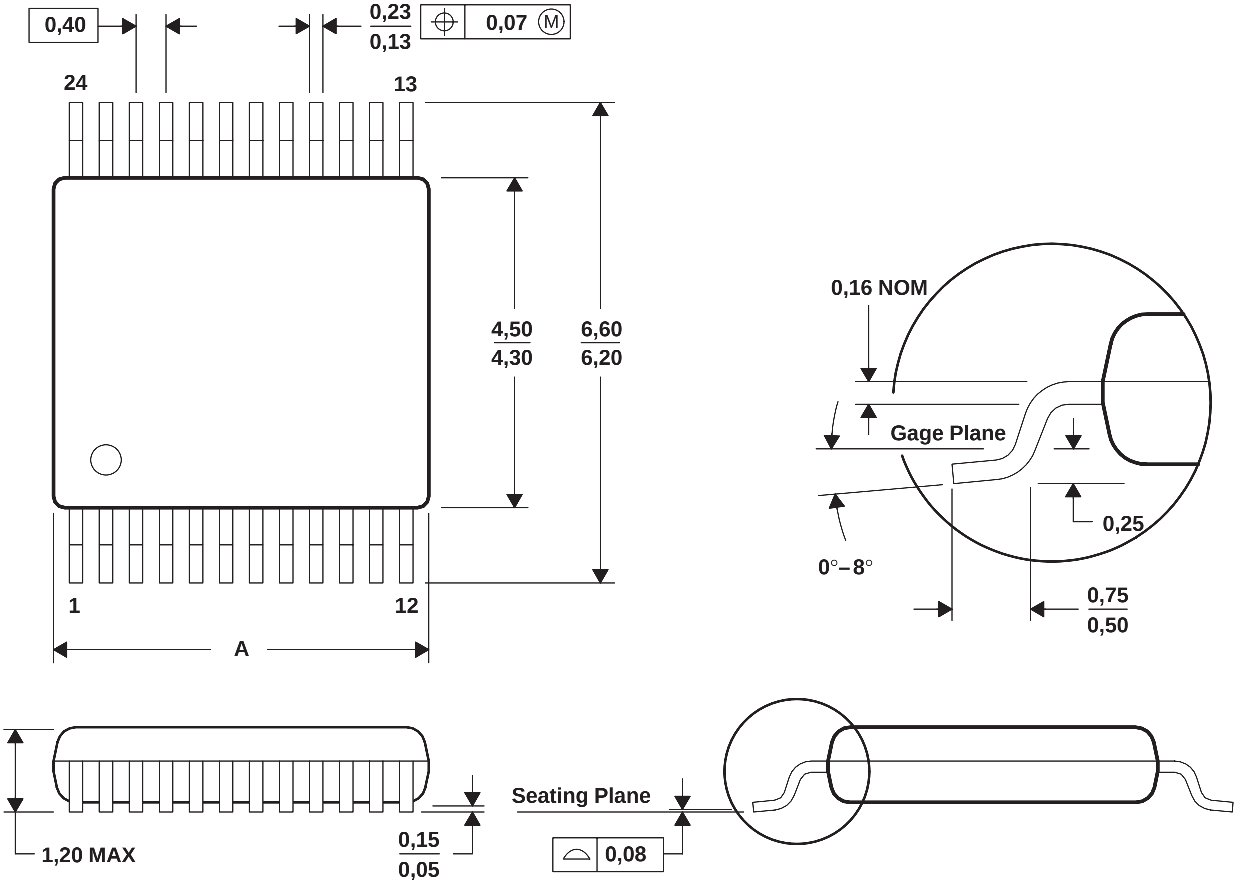
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DGV (R-PDSO-G**) PLASTIC SMALL-OUTLINE

24 PINS SHOWN



PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins – MO-153
  14/16/20/56 Pins – MO-194

GENERIC PACKAGE VIEW

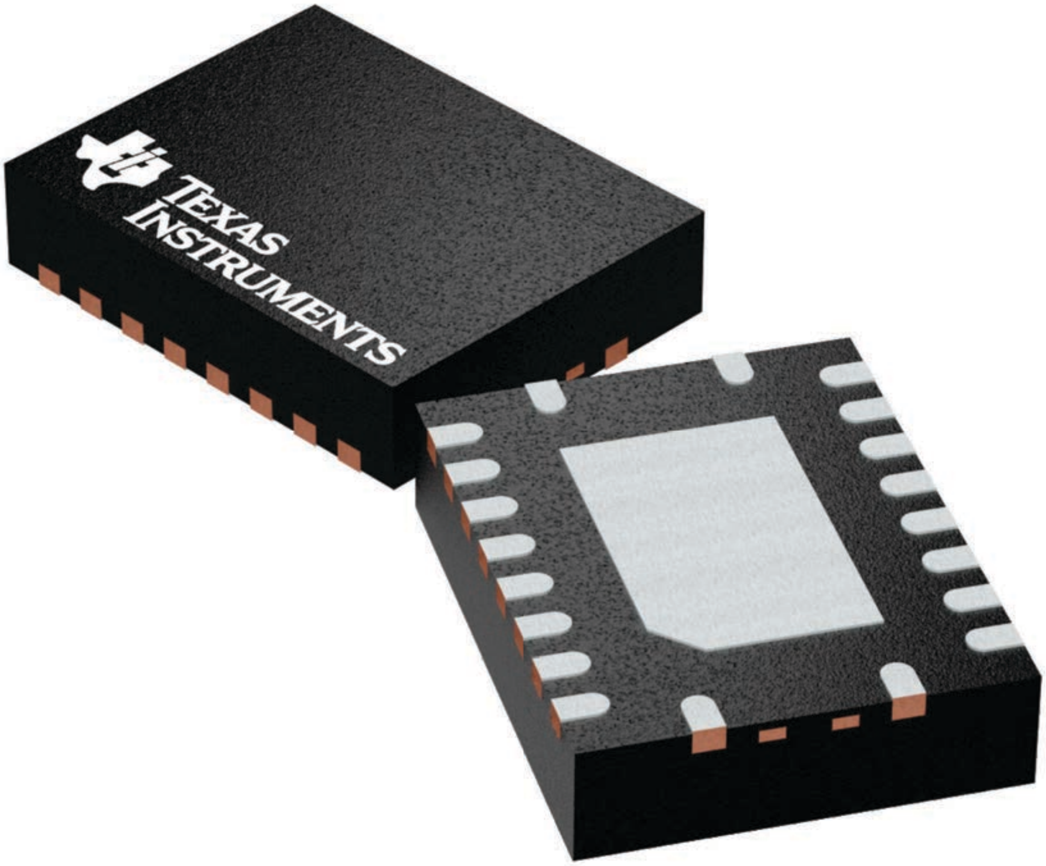
RGY 20

VQFN - 1 mm max height

3.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



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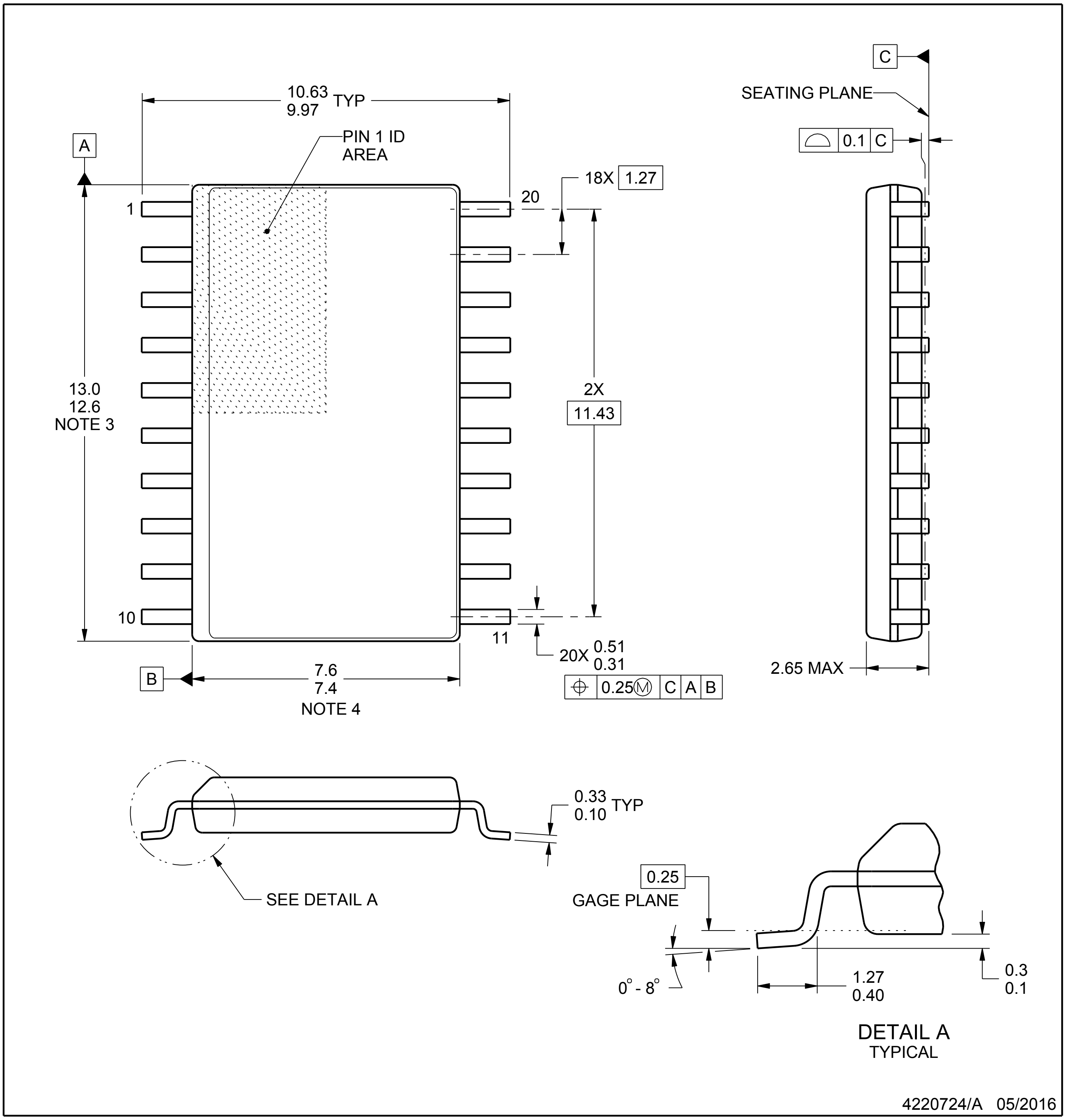
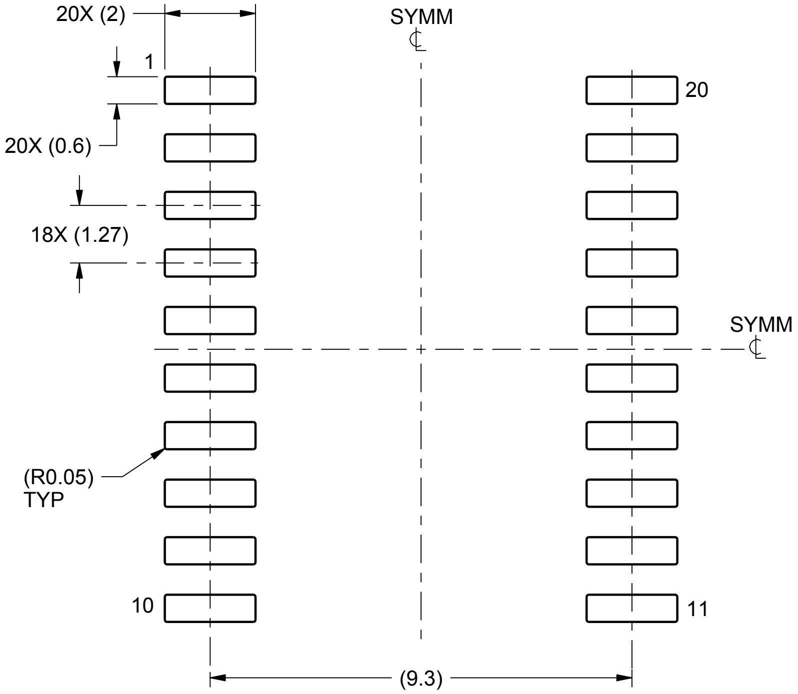
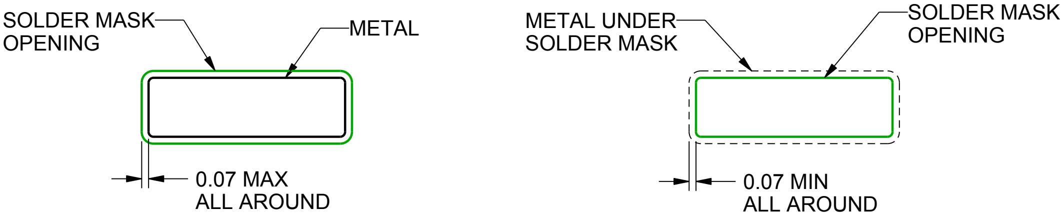


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X



NON SOLDER MASK
DEFINED

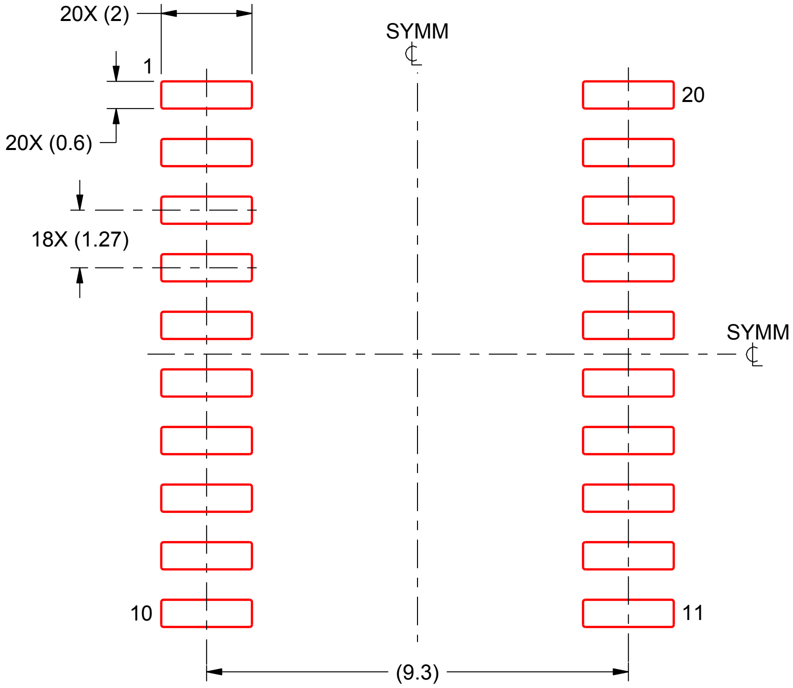
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

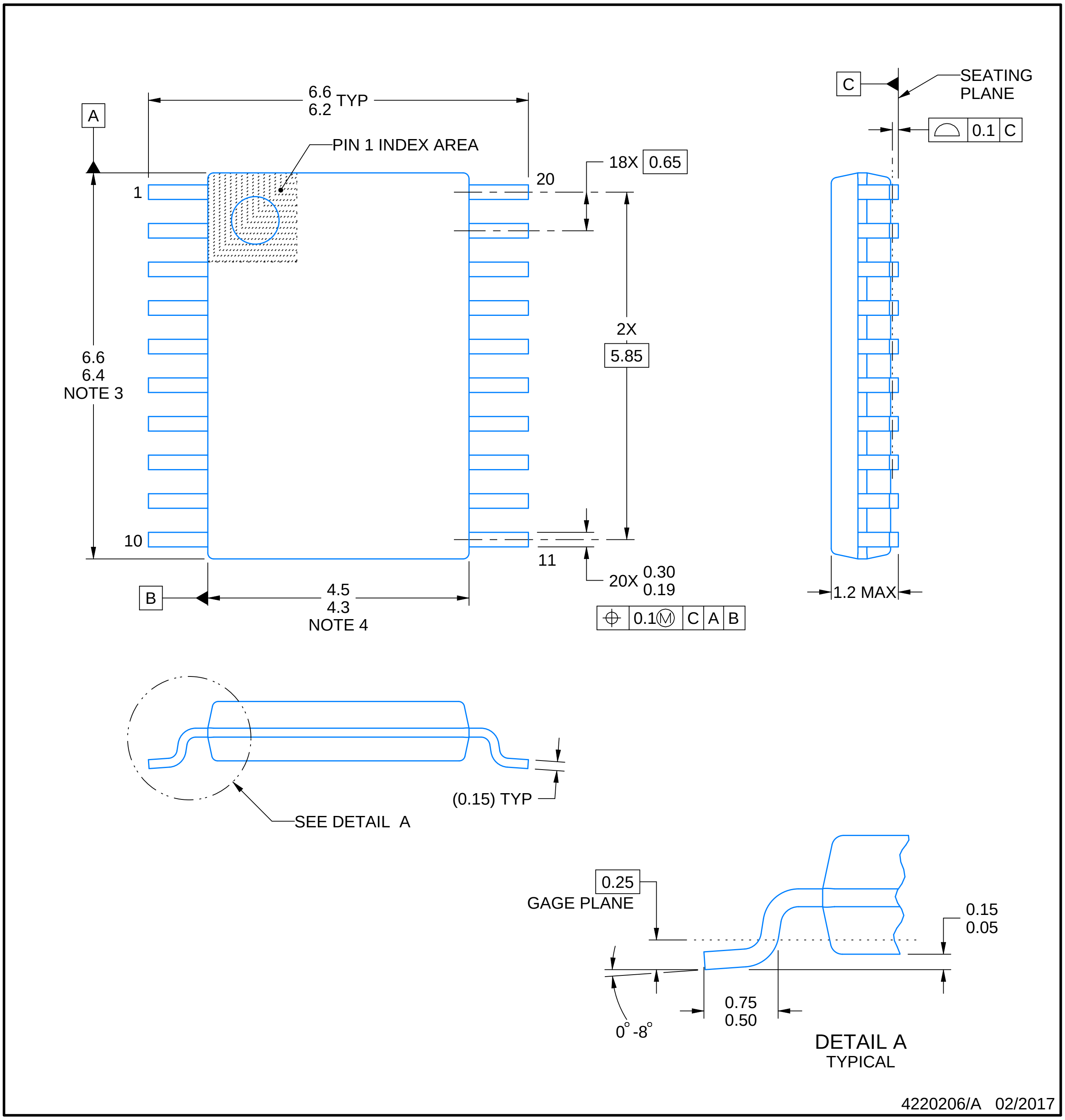
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

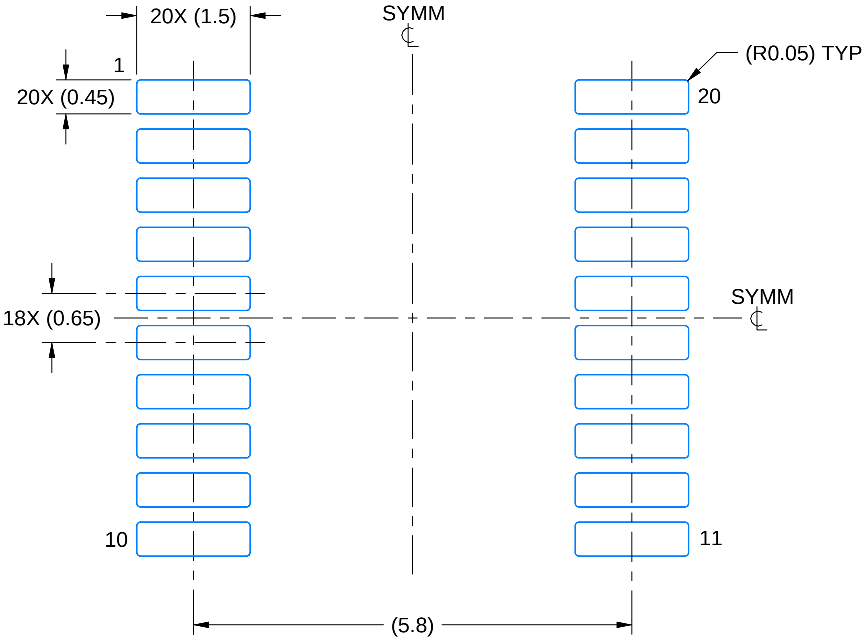
SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

NON-SOLDER MASK
DEFINED
(PREFERRED)

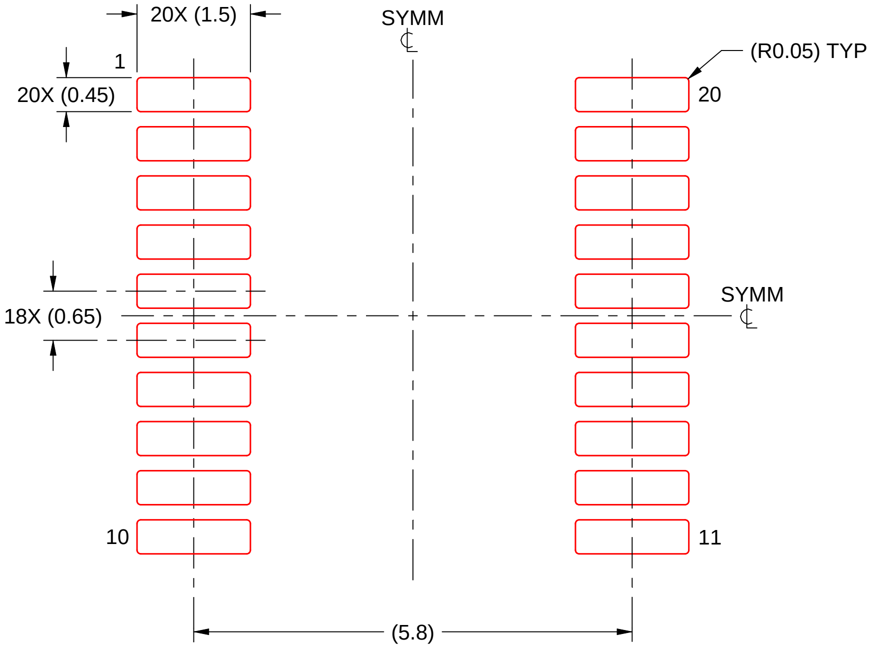
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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